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**UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Kuo-Chuan Liu, et al.  
Confirmation No.: 7648  
Serial No.: 10/066,485  
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For: *Method for Joining Conductive Structures  
and an Electrical Conductive Article*  
Art Group Unit: 1733  
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Atty. Dkt.: 6136/53592 (25916-125)

**CERTIFICATE OF  
MAILING/TRANSMISSION  
(37 C.F.R. § 1.8A)**

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Date

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Mail Stop Issue Fee  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**LETTER TRANSMITTING FORMAL DRAWINGS  
TO THE OFFICIAL DRAFTSPERSON**

Sir:

Transmitted herewith are formal drawings for the above-identified application bearing  
Figures 1A – 125 on forty-eight (48) drawing sheets.

August 20, 2004  
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Respectfully submitted,

By

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